

Docket No.: IRV1.PAU.53

Patent Application

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Pepe, et al.

Examiner: Vu, Hung K.

Serial No.: 09/938,686

Art Unit: 2811

Filed: October 30, 2001

Title: METHOD OF MAKING STACKABLE  
LAYERS CONTAINING  
ENCAPSULATED INTEGRATED  
CIRCUIT CHIPS WITH ONE OR  
MORE OVERLYING INTERCONNECT  
LAYERS

Irvine, California

February 19, 2004

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**REQUEST FOR THREE-MONTH EXTENSION OF TIME**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Applicants request a three-month extension of time from November 21, 2003 to February 21, 2004 to respond to the Office Action of August 21, 2003.

Our check in the amount of \$475.00 to cover the fee for such an extension of time is enclosed. Applicants are entitled to small entity status.

Please charge any additional fees to our Deposit Account No. 01-1960. One copy of this letter is enclosed for such purpose.

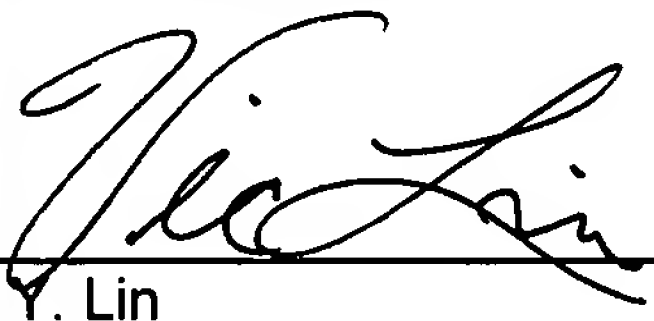
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Commissioner for Patents, P.O. Box 1450,  
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February 19, 2004.

By Angela Williams

Signature  
February 19, 2004

Respectfully submitted,

  
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